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UTILITY SERIAL NUMBER 48/478114		PATENT DATE 16 1999		PATENT NUMBER
5985692		[Redacted]		

SERIAL NUMBER 08/478,114	FILING DATE 06/07/95	385 % 481	SS 106	GROUP ART UNIT 2501	EXAMINER 1107
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APPLICANT: PAUL POENISCH, SANTA CLARA, CA; JAMES A. MATTHEWS, MILPITAS, CA; TRANCY TSAO, SARATOGA, CA.

CONTINUING DATA VERIFIED NONE

FOREIGN/PCT APPLICATIONS VERIFIED NONE

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Foreign priority claimed	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no	AS FILED	STATE OR COUNTRY	SHEETS DRWGS.	TOTAL CLAIMS	INDEP. CLAIMS	FILING FEE RECEIVED	ATTORNEY'S DOCKET NO.
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KENNETH L. CASE
WILLIAM BRINKS HOFFER GILSON & LITTON
2000 K STREET NW
SUITE 200
WASHINGTON DC 20006-1209

McDermott, Will & Emery
600 13th Street, N.W.
Washington, D.C. 20005

TITLE: LOW COST, HIGH PERFORMANCE FLIP-CHIP BONDING TECHNIQUE PROCESS FOR FLIP-CHIP BONDING A SEMICONDUCTOR DIE HAVING GOLD BUMP ELECTRODES

U.S. DEPT. OF COMM./PAT. & TM—PTO-436L (Rev.12-84)

9-24-97

PARTS OF APPLICATION FILED SEPARATELY		ROSS Applications Examiner	
NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
9.29.97		Total Claims	Print Claim
Assistant Examiner		31	1
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
1290.00	12-17-97	5	8
Label Area		Print Fig.	1, 2
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PREPARED FOR ISSUE			

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